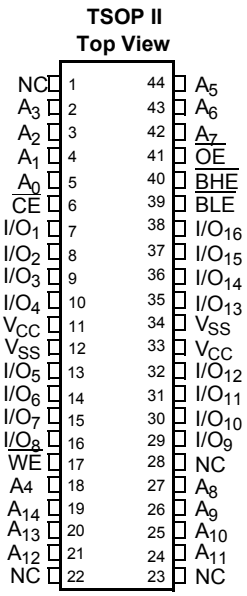
Contents

Selection Guide

Description		-10	-12	-15	Unit
Maximum Access Time		10	12	15	ns
Maximum Operating Current	Commercial/Industrial	90	85	80	mA
	Automotive	–	–	85	mA
Maximum CMOS Standby Current	Commercial/Industrial	5	5	5	mA
	Automotive	–	–	10	mA

Pin Configuration

Figure 1. 44-pin TSOP Type II pinout (Top View) [1]



Note
1. NC pins are not connected on the die.

Pin Definitions

Pin Name	Pin Number	I/O Type	Description
A_0–A_{14}	5, 4, 3, 2, 18, 44, 43, 42, 27, 26, 25, 24, 21, 20, 19	Input	**Address Inputs used to select one of the address locations**.
I/O_1–I/O_{16}	7–10, 13–16, 29–32, 35–38	Input/Output	**Bidirectional Data I/O lines**. Used as input or output lines depending on operation.
NC	1, 22, 23, 28	No Connect	**No Connects**. Not connected to the die.
$\overline{WE}$	17	Input/Control	**Write Enable Input, active LOW**. When selected LOW, a Write is conducted. When deselected HIGH, a Read is conducted.
$\overline{CE}$	6	Input/Control	**Chip Enable Input, active LOW**. When LOW, selects the chip. When HIGH, deselects the chip.
$\overline{BHE}$, $\overline{BLE}$	40, 39	Input/Control	**Byte Write Select Inputs, active LOW**. $\overline{BHE}$ controls I/O_{16}–I/O_9, $\overline{BLE}$ controls I/O_8–I/O_1.
$\overline{OE}$	41	Input/Control	**Output Enable, active LOW**. Controls the direction of the I/O pins. When LOW, the I/O pins are allowed to behave as outputs. When deasserted HIGH, I/O pins are tri-stated, and act as input data pins.
V_{SS}	12, 34	Ground	**Ground for the device**. Should be connected to ground of the system.
V_{CC}	11, 33	Power Supply	**Power Supply inputs to the device.**

Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Storage temperature ..... –65 °C to +150 °C

Ambient temperature with power applied ..... –55 °C to +125 °C

Supply voltage on V_{CC} to relative GND [2] .....–0.5 V to +4.6 V

DC voltage applied to outputs in high Z State [2] .....–0.5 V to V_{CC} + 0.5 V

DC input voltage [2] .....–0.5 V to V_{CC} + 0.5 V

Current into outputs (LOW) ..... 20 mA

Static discharge voltage (per MIL-STD-883, method 3015) ..... > 2001 V

Latch-up current ..... > 200 mA

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	0 °C to +70 °C	3.3 V ± 10%
Industrial	–40 °C to +85 °C	3.3 V ± 10%
Automotive	–40 °C to +125 °C	3.3 V ± 10%

Electrical Characteristics

Over the Operating Range

Parameter	Description	Test Conditions		-10		-12		-15		Unit
				Min	Max	Min	Max	Min	Max	
V_{OH}	Output HIGH voltage	V_{CC} = Min, I_{OH} = –4.0 mA		2.4	–	2.4	–	2.4	–	V
V_{OL}	Output LOW voltage	V_{CC} = Min, I_{OL} = 8.0 mA		–	0.4	–	0.4	–	0.4	V
V_{IH}	Input HIGH voltage			2.0	V_{CC} + 0.3	2.0	V_{CC} + 0.3	2.0	V_{CC} + 0.3	V
V_{IL}	Input LOW voltage [2]			–0.3	0.8	–0.3	0.8	–0.3	0.8	V
I_{IX}	Input leakage current	GND ≤ V_I ≤ V_{CC}	Commercial / Industrial	–1	+1	–1	+1	–1	+1	µA
			Automotive	–	–	–	–	–20	+20	µA
I_{OZ}	Output leakage current	GND ≤ V_I ≤ V_{CC}, Output Disabled	Commercial / Industrial	–1	+1	–1	+1	–1	+1	µA
			Automotive	–	–	–	–	–20	+20	µA
I_{CC}	V_{CC} operating supply current	V_{CC} = Max, I_{OUT} = 0 mA, f = f_{MAX} = $1/t_{RC}$	Commercial / Industrial	–	90	–	85	–	80	mA
			Automotive	–	–	–	–	–	85	mA
I_{SB1}	Automatic CE power-down current – TTL Inputs	Max V_{CC}, $\overline{CE}$ ≥ V_{IH}, V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{MAX}	Commercial / Industrial	–	15	–	15	–	15	mA
			Automotive	–	–	–	–	–	20	mA
I_{SB2}	Automatic CE power-down current – CMOS inputs	Max V_{CC}, $\overline{CE}$ ≥ V_{CC} – 0.3 V, V_{IN} ≥ V_{CC} – 0.3 V, or V_{IN} ≤ 0.3 V, f = 0	Commercial / Industrial	–	5	–	5	–	5	mA
			Automotive	–	–	–	–	–	10	mA

Note
2. V_{IL}(min) = –2.0 V and V_{IH}(max) = V_{CC} + 0.5 V for pulse durations of less than 20 ns.

Capacitance

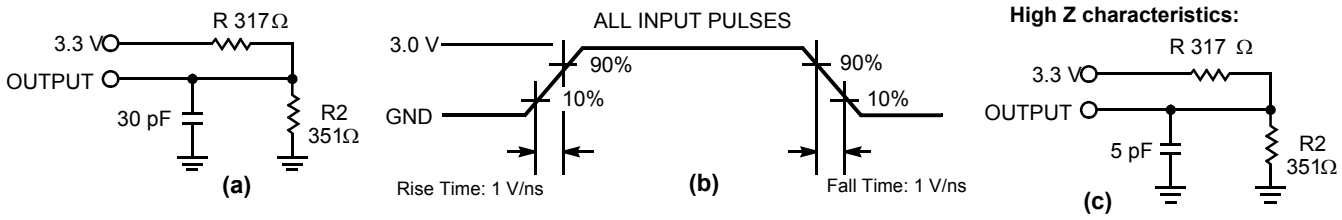
Parameter [3]	Description	Test Conditions	Max	Unit
C_{IN}	Input capacitance	T_A = 25 °C, f = 1 MHz, V_{CC} = 3.3 V	8	pF
C_{OUT}	Output capacitance		8	pF

Thermal Resistance

Parameter [3]	Description	Test Conditions	44-pin TSOP-II	Unit
Θ_{JA}	Thermal resistance (junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, per EIA/JESD51.	76.92	°C/W
Θ_{JC}	Thermal resistance (junction to case)		15.86	°C/W

AC Test Loads and Waveforms

Figure 2. AC Test Loads and Waveforms [4]



Notes
3. Tested initially and after any design or process changes that may affect these parameters.
4. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5 V, input pulse levels of 0 to 3.0 V.

Switching Characteristics

Over the Operating Range

Parameter [5]	Description	-10		-12		-15		Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle								
t_{RC}	Read cycle time	10	–	12	–	15	–	ns
t_{AA}	Address to data valid	–	10	–	12	–	15	ns
t_{OHA}	Data hold from address change	3	–	3	–	3	–	ns
t_{ACE}	$\overline{CE}$ LOW to data valid	–	10	–	12	–	15	ns
t_{DOE}	$\overline{OE}$ LOW to data valid	–	5	–	6	–	7	ns
t_{LZOE}	$\overline{OE}$ LOW to low Z[6]	0	–	0	–	0	–	ns
t_{HZOE}	$\overline{OE}$ HIGH to high Z[6, 7]	–	5	–	6	–	7	ns
t_{LZCE}	$\overline{CE}$ LOW to low Z[6]	3	–	3	–	3	–	ns
t_{HZCE}	$\overline{CE}$ HIGH to high Z[6, 7]	–	5	–	6	–	7	ns
t_{PU}[8]	$\overline{CE}$ LOW to power-up	0	–	0	–	0	–	ns
t_{PD}[8]	$\overline{CE}$ HIGH to power-down	–	10	–	12	–	15	ns
t_{DBE}	Byte enable to data valid	–	5	–	6	–	7	ns
t_{LZBE}	Byte enable to low Z	0	–	0	–	0	–	ns
t_{HZBE}	Byte disable to high Z	–	5	–	6	–	7	ns
Write Cycle[9]								
t_{WC}	Write cycle time	10	–	12	–	15	–	ns
t_{SCE}	$\overline{CE}$ LOW to write end	8	–	9	–	10	–	ns
t_{AW}	Address set-up to write end	7	–	8	–	10	–	ns
t_{HA}	Address hold from write end	0	–	0	–	0	–	ns
t_{SA}	Address set-up to write start	0	–	0	–	0	–	ns
t_{PWE}	$\overline{WE}$ pulse width	7	–	8	–	10	–	ns
t_{SD}	Data set-up to write end	5	–	6	–	8	–	ns
t_{HD}	Data hold from write end	0	–	0	–	0	–	ns
t_{LZWE}	$\overline{WE}$ HIGH to low Z[6]	3	–	3	–	3	–	ns
t_{HZWE}	$\overline{WE}$ LOW to high Z[6, 7]	–	5	–	6	–	7	ns
t_{BW}	Byte enable to end of write	7	–	8	–	9	–	ns

Notes

5. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5 V, input pulse levels of 0 to 3.0 V.
6. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
7. t_{HZOE}, t_{HZBE}, t_{HZCE}, and t_{HZWE} are specified with a load capacitance of 5 pF as in part (c) of AC Test Loads. Transition is measured ± 500 mV from steady-state voltage.
8. This parameter is guaranteed by design and is not tested.
9. The internal Write time of the memory is defined by the overlap of $\overline{CE}$ LOW, $\overline{WE}$ LOW and $\overline{BHE}$/$\overline{BLE}$ LOW. $\overline{CE}$, $\overline{WE}$ and $\overline{BHE}$/$\overline{BLE}$ must be LOW to initiate a Write, and the transition of these signals can terminate the Write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the Write.

Switching Waveforms

Figure 3. Read Cycle No. 1 [10, 11]

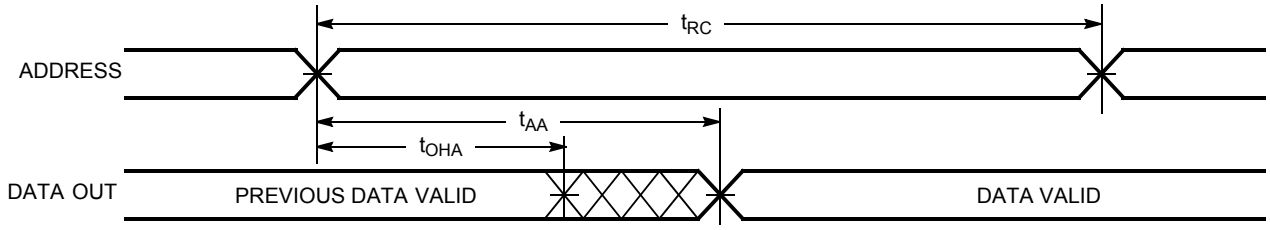
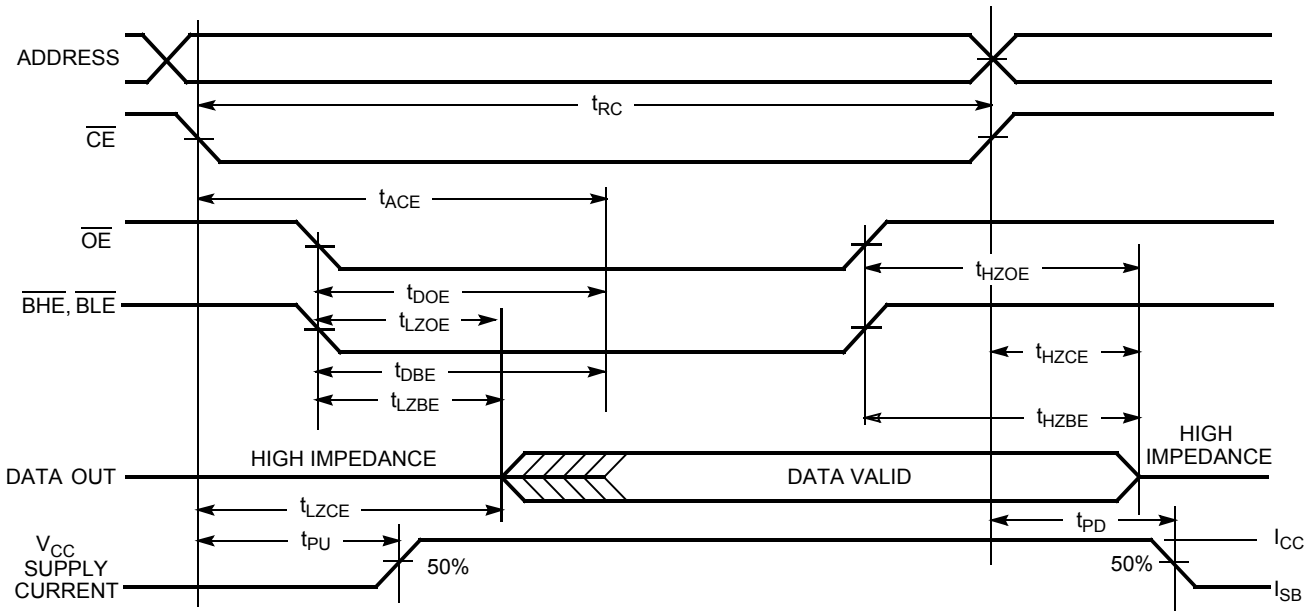


Figure 4. Read Cycle No. 2 ($\overline{OE}$ Controlled) [11, 12]



Notes
10. Device is continuously selected. $\overline{OE}$, $\overline{CE}$, $\overline{BHE}$ and/or $\overline{BHE}$ = V_{IL}.
11. $\overline{WE}$ is HIGH for Read cycle.
12. Address valid prior to or coincident with $\overline{CE}$ transition LOW.

Switching Waveforms *(continued)*

Figure 5. Write Cycle No. 1 ($\overline{CE}$ Controlled) [13, 14]

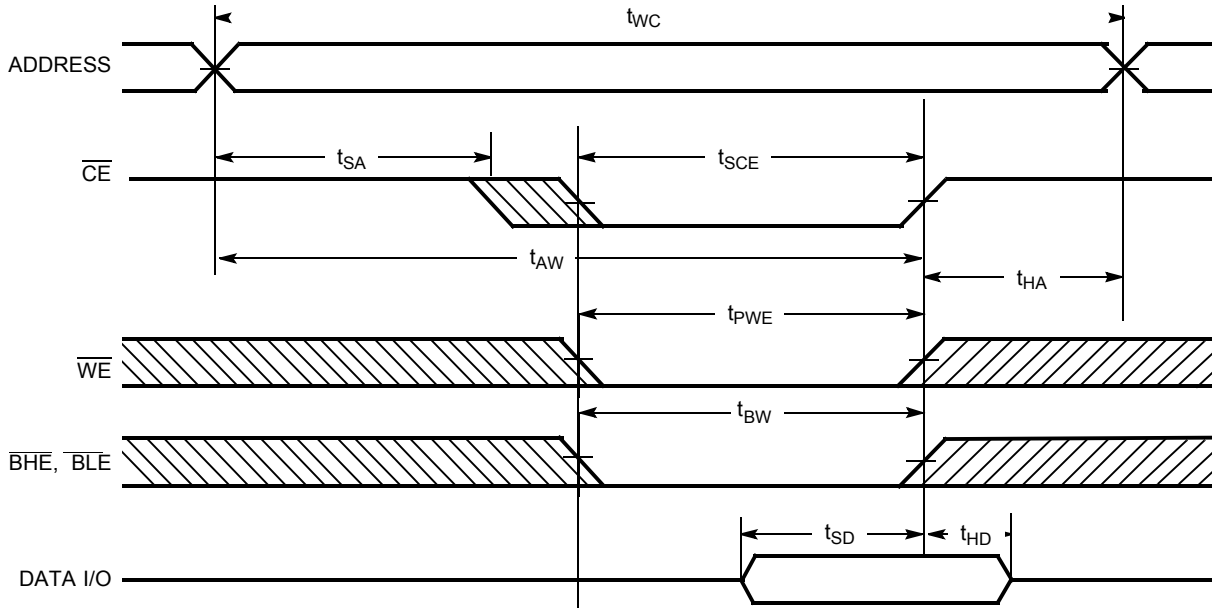
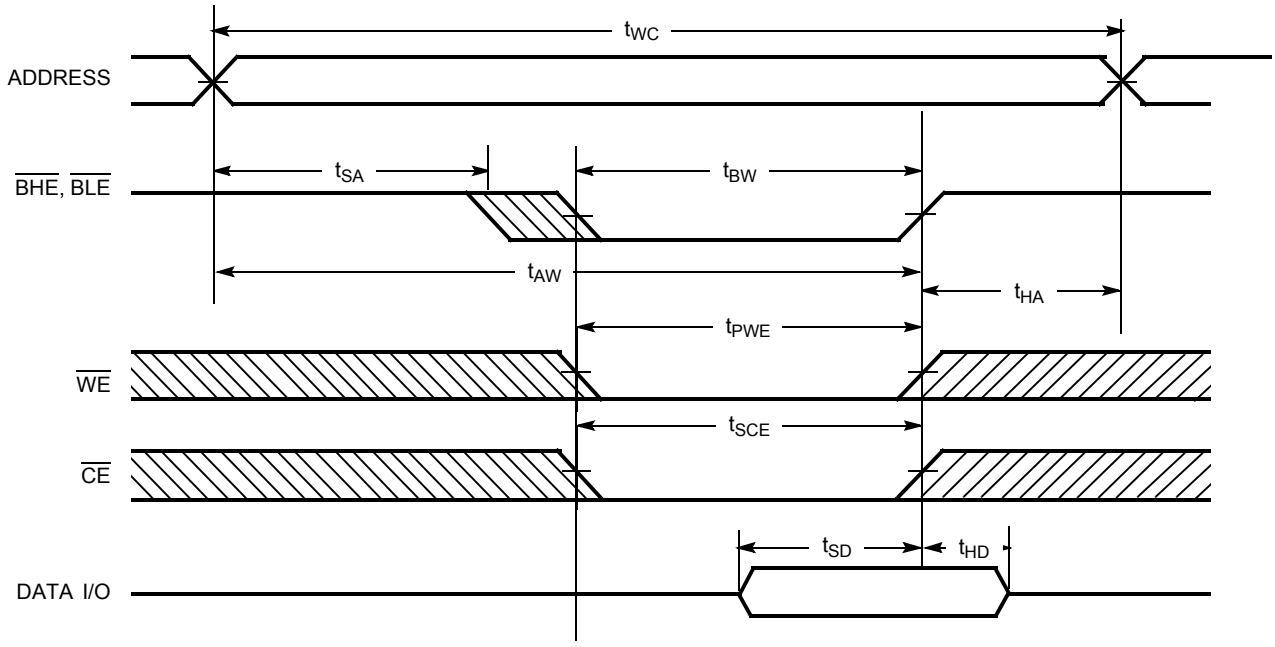


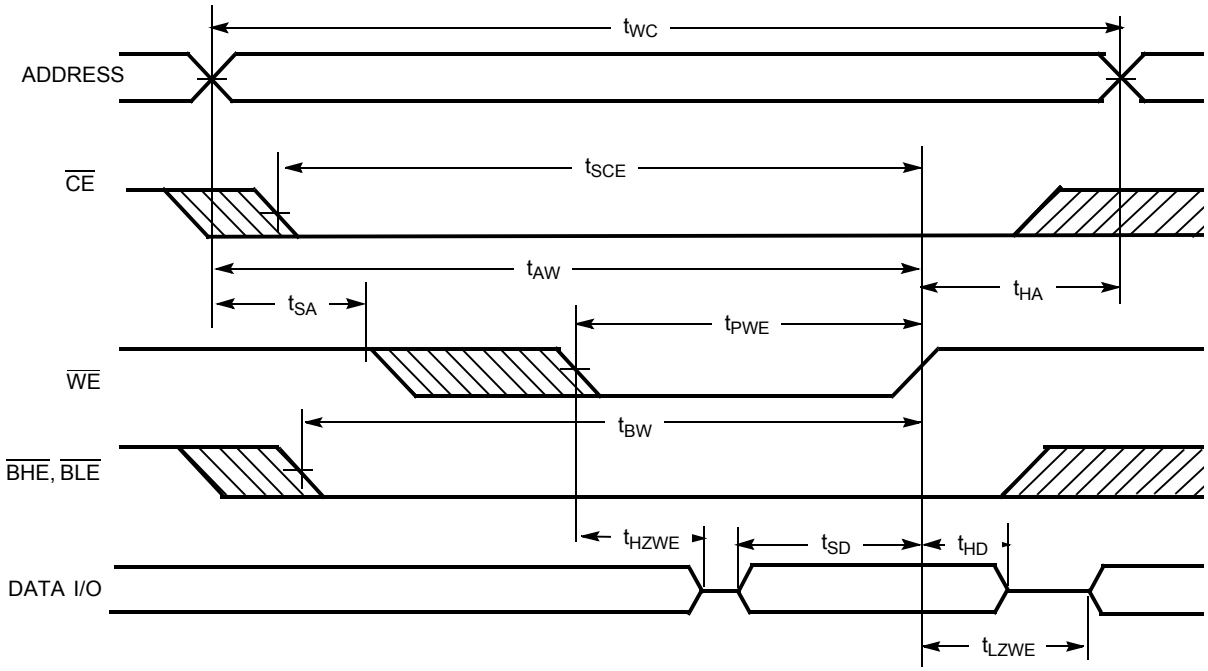
Figure 6. Write Cycle No. 2 ($\overline{BLE}$ or $\overline{BHE}$ Controlled)



Notes
13. Data I/O is high impedance if $\overline{OE}$ or $\overline{BHE}$ and/or $\overline{BLE}$ = V_{IH}.
14. If $\overline{CE}$ goes HIGH simultaneously with $\overline{WE}$ going HIGH, the output remains in a high-impedance state.

Switching Waveforms *(continued)*

Figure 7. Write Cycle No. 3 ($\overline{WE}$ Controlled, $\overline{OE}$ LOW)



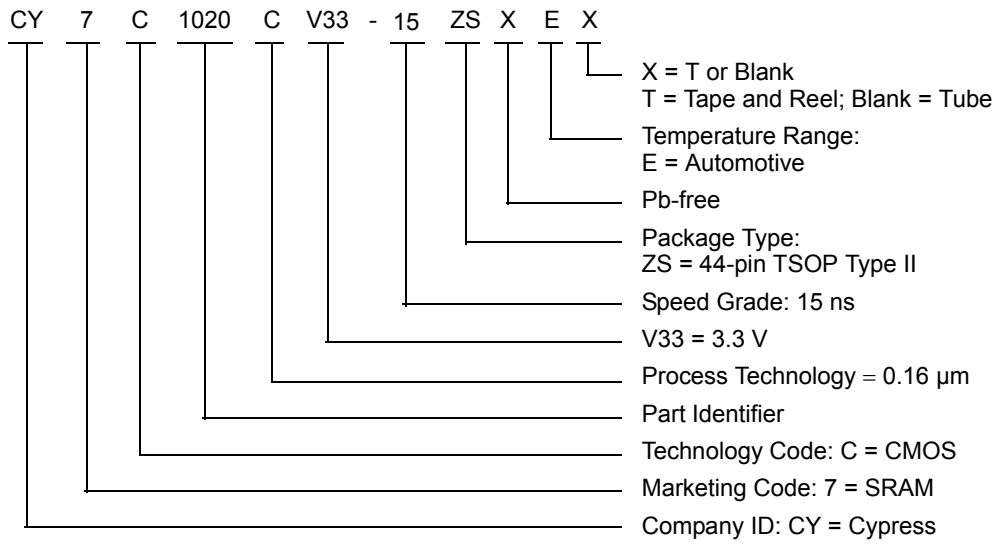
Truth Table

$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	$\overline{BLE}$	$\overline{BHE}$	$I/O_1–I/O_8$	$I/O_9–I/O_{16}$	Mode	Power
H	X	X	X	X	High Z	High Z	Power-down	Standby (I_{SB})
L	L	H	L	L	Data out	Data out	Read – All bits	Active (I_{CC})
			L	H	Data out	High Z	Read – Lower bits only	Active (I_{CC})
			H	L	High Z	Data out	Read – Upper bits only	Active (I_{CC})
L	X	L	L	L	Data in	Data in	Write – All bits	Active (I_{CC})
			L	H	Data in	High Z	Write – Lower bits only	Active (I_{CC})
			H	L	High Z	Data in	Write – Upper bits only	Active (I_{CC})
L	H	H	X	X	High Z	High Z	Selected, outputs disabled	Active (I_{CC})
L	X	X	H	H	High Z	High Z	Selected, outputs disabled	Active (I_{CC})

Ordering Information

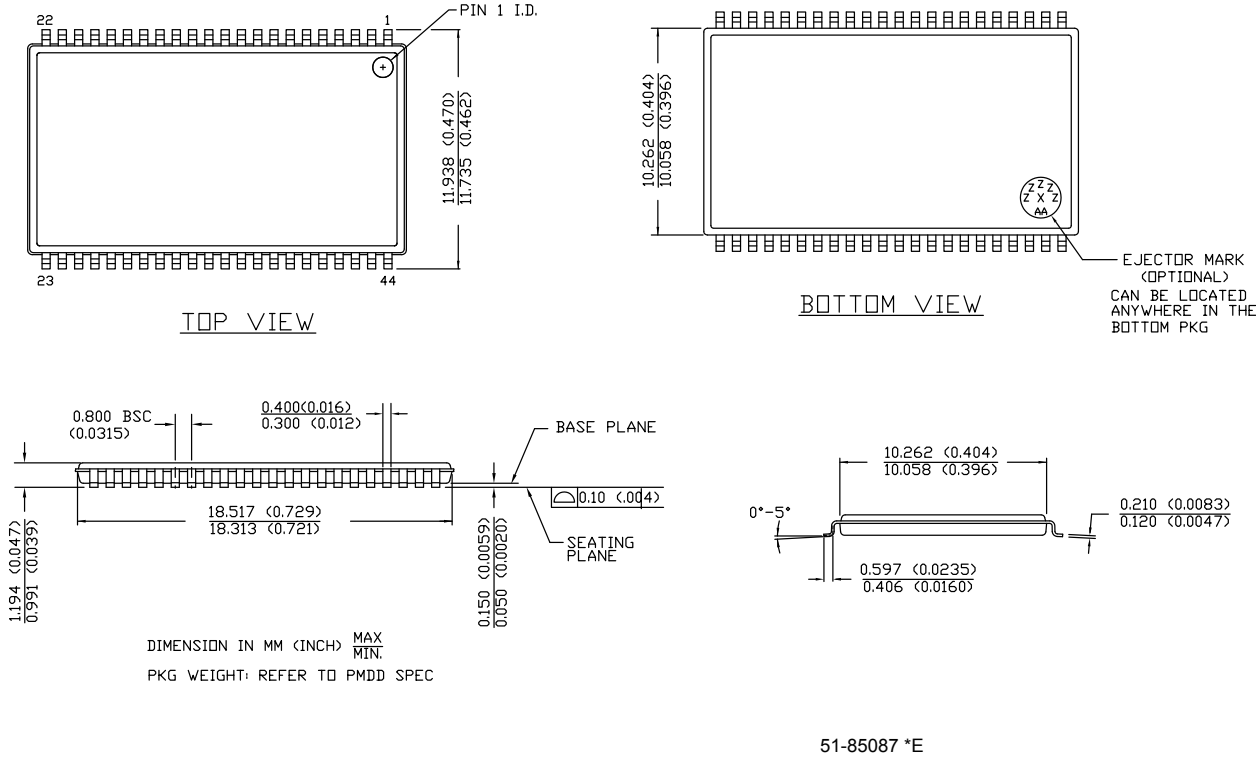
Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
15	CY7C1020CV33-15ZSXE	51-85087	44-pin TSOP Type II (Pb-free)	Automotive
	CY7C1020CV33-15ZSXET	51-85087	44-pin TSOP Type II (Pb-free)	Automotive

Ordering Code Definitions



Package Diagrams

Figure 8. 44-pin TSOP Z44-II Package Outline, 51-85087



Acronyms

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
$\overline{CE}$	Chip Enable
I/O	Input/Output
$\overline{OE}$	Output Enable
SRAM	Static Random Access Memory
TSOP	Thin Small-Outline Package
TTL	Transistor-Transistor Logic
$\overline{WE}$	Write Enable

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
MHz	megahertz
µA	microampere
mA	milliampere
mW	milliwatt
ns	nanosecond
%	percent
pF	picofarad
V	volt
W	watt

Document History Page

Document Title: CY7C1020CV33, 512 K (32 K × 16) Static RAM Document Number: 38-05133				
Rev.	**ECN No.**	**Issue Date**	**Orig. of Change**	**Description of Change**
**	109428	12/16/01	HGK	New data sheet.
*A	115045	05/30/02	HGK	I_{CC} and I_{SB1} data modified
*B	117615	08/14/02	DFP	Pin 1= NC Pin 18 = A4; remove SOJ package option; remove 8ns option.
*C	262949	See ECN	RKF	Added Automotive Specs to Data sheet
*D	334398	See ECN	SYT	Added Lead-Free Product Information
*E	493543	See ECN	NXR	Added note #1 on page #1 Changed the description of I_{IX} from Input Load Current to Input Leakage Current in DC Electrical Characteristics table Removed I_{OS} parameter from DC Electrical Characteristics table Updated Ordering Information Table
*F	2897691	03/23/2010	RAME	Updated Ordering Information Updated Package Diagrams.
*G	3057593	10/13/2010	PRAS	Updated Ordering Information and added Ordering Code Definitions.
*H	3100106	12/02/2010	PRAS	Added Acronyms and Units of Measure. Minor edits and updated in new template.
*I	4146968	10/04/2013	VINI	Updated Package Diagrams: spec 51-85087 – Changed revision from *C to *E. Updated in new template. Completing Sunset Review.
*J	4567799	11/12/2014	VINI	Updated Functional Description: Added “For a complete list of related resources, click here.” at the end. Updated Switching Characteristics: Added Note 10 and referred the same note in “Write Cycle”. Updated Switching Waveforms: Added Note 16 and referred the same note in Figure 7. Completing Sunset Review.
*K	4573200	11/18/2014	VINI	Added related documentation hyperlink in page 1.

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